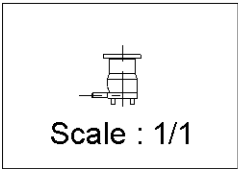
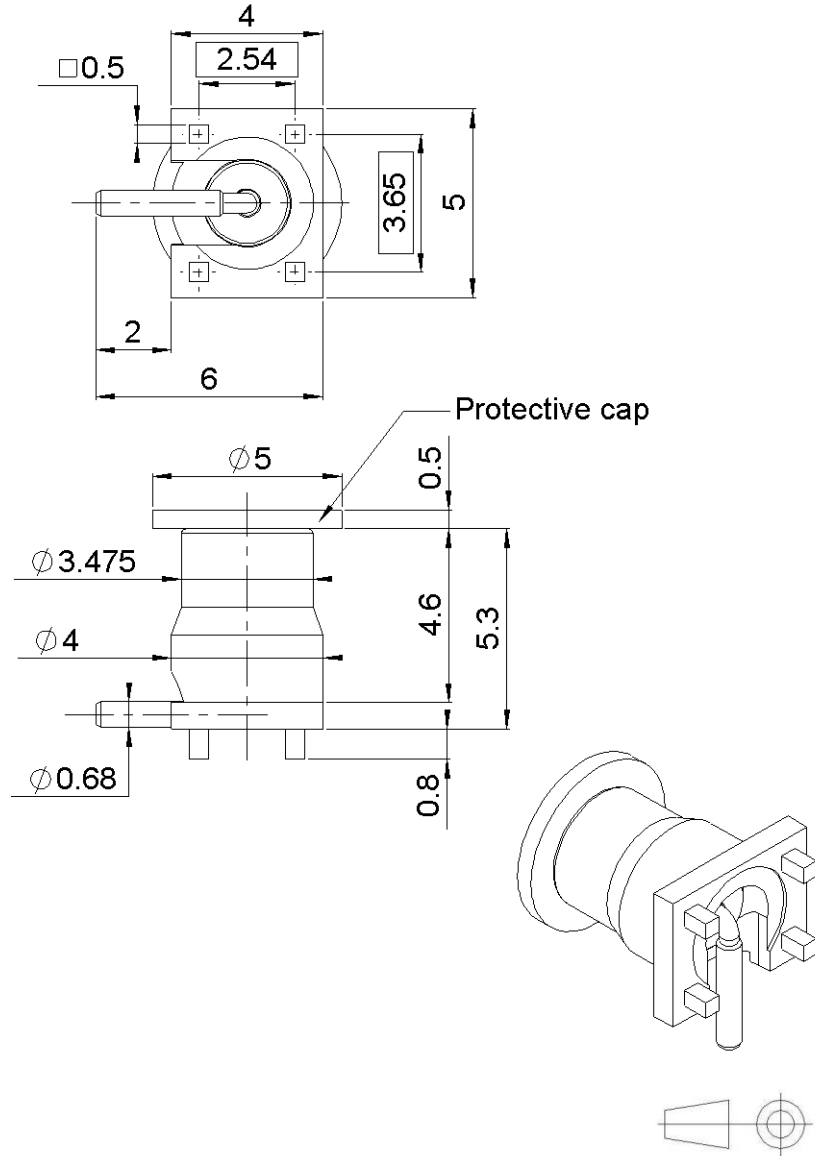


PAGE 1/5	ISSUE 1435C	SERIES <b>MMCX</b>	PART NUMBER <b>R110427830</b>
----------	-------------	--------------------	-------------------------------



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
Body	<b>BRASS</b>	<b>NPGR</b>
Center contact	<b>BERYLLIUM COPPER</b>	<b>GOLD OVER NICKEL</b>
Outer contact	-	-
Insulator	<b>PTFE</b>	-
Gasket	-	-
Others parts	-	-
-	-	-
-	-	-

PAGE 2/5	ISSUE <b>1435C</b>	SERIES <b>MMCX</b>	PART NUMBER <b>R110427830</b>
----------	--------------------	--------------------	-------------------------------

**PACKAGING**

Standard	Unit	Other
<b>500</b>	<b>Contact us</b>	<b>Contact us</b>

**ELECTRICAL CHARACTERISTICS**

Impedance		<b>50</b>	Ω
Frequency		<b>0-6</b>	GHz
VSWR	<b>NA</b>	<b>+</b>	<b>0.0000</b> x F(GHz) Maxi
Insertion loss		<b>NA</b>	√F(GHz) dB Maxi
RF leakage	- (		- F(GHz)) dB Maxi
Voltage rating		<b>250</b>	Veff Maxi
Dielectric withstanding voltage		<b>500</b>	Veff mini
Insulation resistance		<b>1000</b>	MΩ mini

**ENVIRONMENTAL**

Operating temperature	<b>-55/+155</b>	°C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

**MECHANICAL CHARACTERISTICS**

Center contact retention			
Axial force – Mating End	<b>10*</b>		N mini
Axial force – Opposite end	<b>10*</b>		N mini
Torque	<b>NA</b>		N.cm mini
Recommended torque			
Mating	<b>NA</b>		N.cm
Panel nut	<b>NA</b>		N.cm
Mating life	<b>500</b>		Cycles mini
Weight	<b>0.3800</b>		g

**SPECIFICATION**

**1AB052720013**

**OTHER CHARACTERISTICS**

Assembly instruction:

Others:

**\*after soldering**

**Materials are compliant with the EU's**

**RoHS directive**

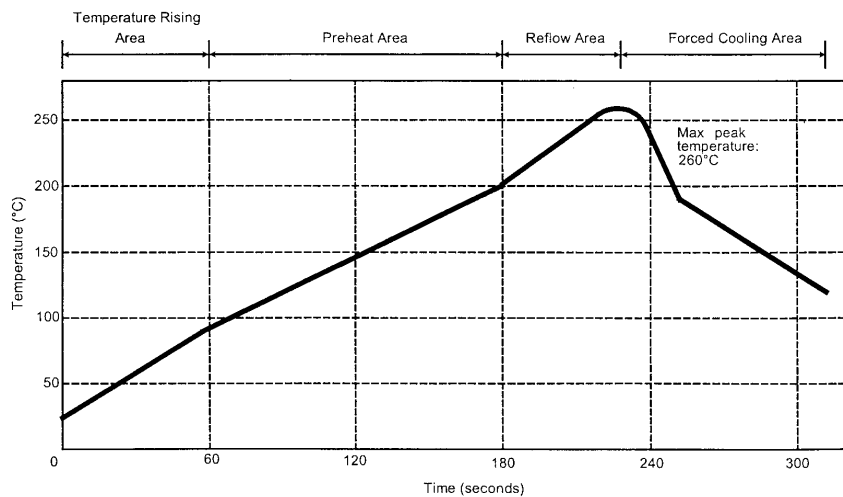
PAGE 3/5	ISSUE 1435C	SERIES MMCX	PART NUMBER R110427830
----------	-------------	-------------	------------------------

### SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .
5. Verification of solder joints and position of the component by visual inspection.

**NOTE :** The receptacle and the plug must not be mated before completion of this procedure

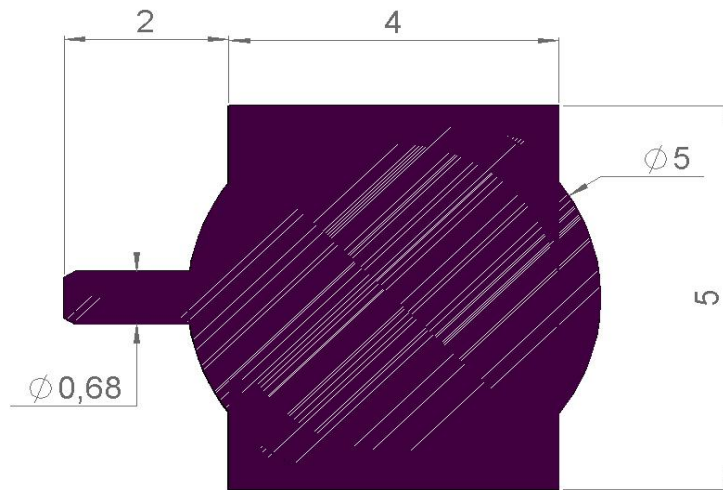
### TEMPERATURE PROFILE



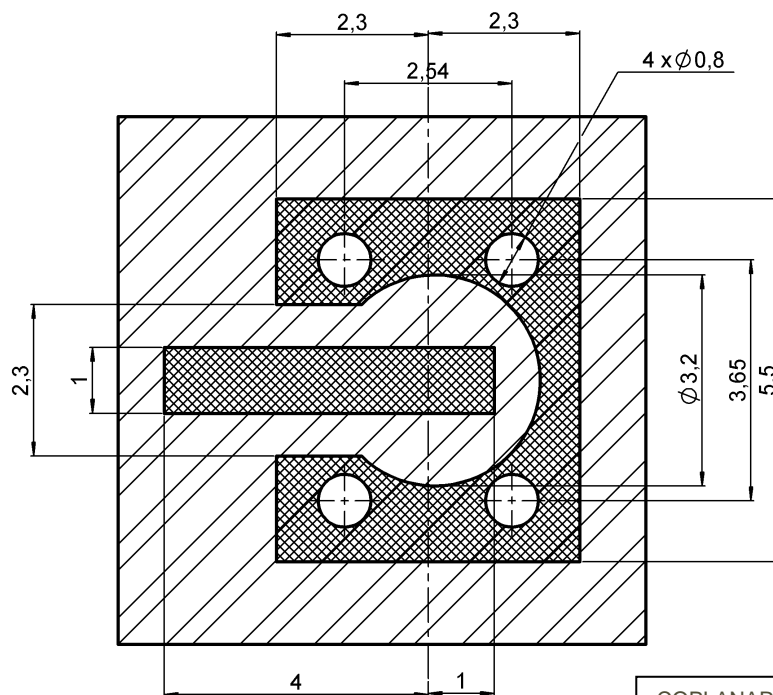
Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec



PAGE 4/5	ISSUE 1435C	SERIES MMCX	PART NUMBER R110427830
----------	-------------	-------------	------------------------

**SHADOW OF RECEPTACLE FOR VIDEO CAMERA**



**STANDARD PAD**



-  Masse + vernis  
Ground + varnish
-  Plots de soudure  
Lands for solder paste

**COPLANAR LINE**  
 Pattern and signal are on the same side.  
 Thickness of the PCB : 1.6 mm  
 The material of the PCB is the epoxy resin of Glass fabrics bacs ( ER : 4.8 ).  
 The solder resist should be printed except for The land pattern on the PCB.

PAGE 5/5	ISSUE 1435C	SERIES MMCX	PART NUMBER R110427830
----------	-------------	-------------	------------------------

